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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	120
Number of Logic Elements/Cells	1200
Total RAM Bits	24576
Number of I/O	93
Number of Gates	113000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	144-BGA
Supplier Device Package	144-FBGA (13x13)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/ep20k30efc144-2x">https://www.e-xfl.com/product-detail/intel/ep20k30efc144-2x</a>

All APEX 20K devices are reconfigurable and are 100% tested prior to shipment. As a result, test vectors do not have to be generated for fault coverage purposes. Instead, the designer can focus on simulation and design verification. In addition, the designer does not need to manage inventories of different application-specific integrated circuit (ASIC) designs; APEX 20K devices can be configured on the board for the specific functionality required.

APEX 20K devices are configured at system power-up with data stored in an Altera serial configuration device or provided by a system controller. Altera offers in-system programmability (ISP)-capable EPC1, EPC2, and EPC16 configuration devices, which configure APEX 20K devices via a serial data stream. Moreover, APEX 20K devices contain an optimized interface that permits microprocessors to configure APEX 20K devices serially or in parallel, and synchronously or asynchronously. The interface also enables microprocessors to treat APEX 20K devices as memory and configure the device by writing to a virtual memory location, making reconfiguration easy.

After an APEX 20K device has been configured, it can be reconfigured in-circuit by resetting the device and loading new data. Real-time changes can be made during system operation, enabling innovative reconfigurable computing applications.

APEX 20K devices are supported by the Altera Quartus II development system, a single, integrated package that offers HDL and schematic design entry, compilation and logic synthesis, full simulation and worst-case timing analysis, SignalTap logic analysis, and device configuration. The Quartus II software runs on Windows-based PCs, Sun SPARCstations, and HP 9000 Series 700/800 workstations.

The Quartus II software provides NativeLink interfaces to other industry-standard PC- and UNIX workstation-based EDA tools. For example, designers can invoke the Quartus II software from within third-party design tools. Further, the Quartus II software contains built-in optimized synthesis libraries; synthesis tools can use these libraries to optimize designs for APEX 20K devices. For example, the Synopsys Design Compiler library, supplied with the Quartus II development system, includes DesignWare functions optimized for the APEX 20K architecture.

## Logic Array Block

Each LAB consists of 10 LEs, the LEs' associated carry and cascade chains, LAB control signals, and the local interconnect. The local interconnect transfers signals between LEs in the same or adjacent LABs, IOEs, or ESBs. The Quartus II Compiler places associated logic within an LAB or adjacent LABs, allowing the use of a fast local interconnect for high performance. Figure 3 shows the APEX 20K LAB.

APEX 20K devices use an interleaved LAB structure. This structure allows each LE to drive two local interconnect areas. This feature minimizes use of the MegaLAB and FastTrack interconnect, providing higher performance and flexibility. Each LE can drive 29 other LEs through the fast local interconnect.

**Figure 3. LAB Structure**

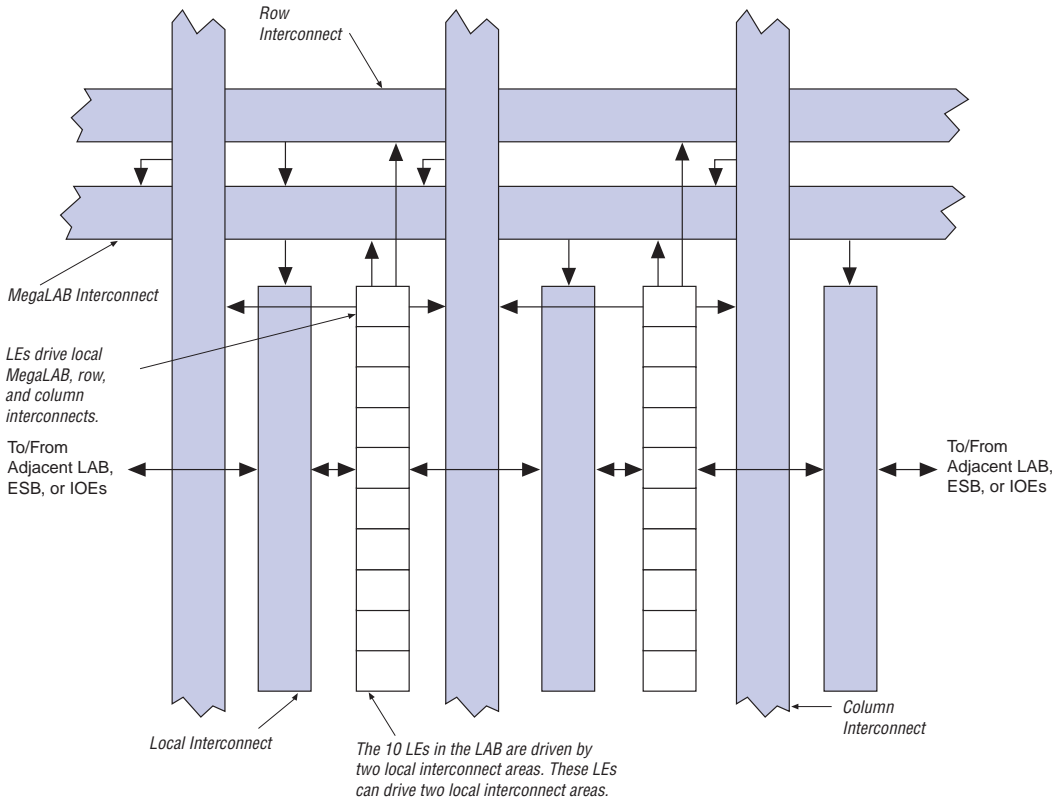
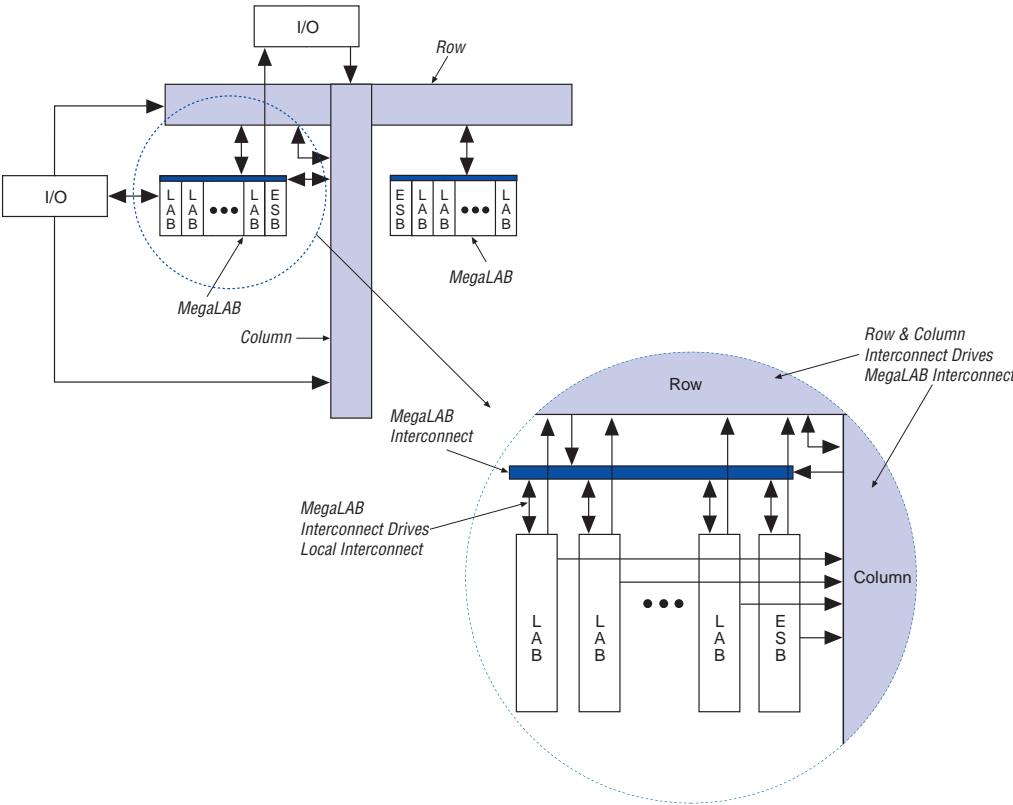
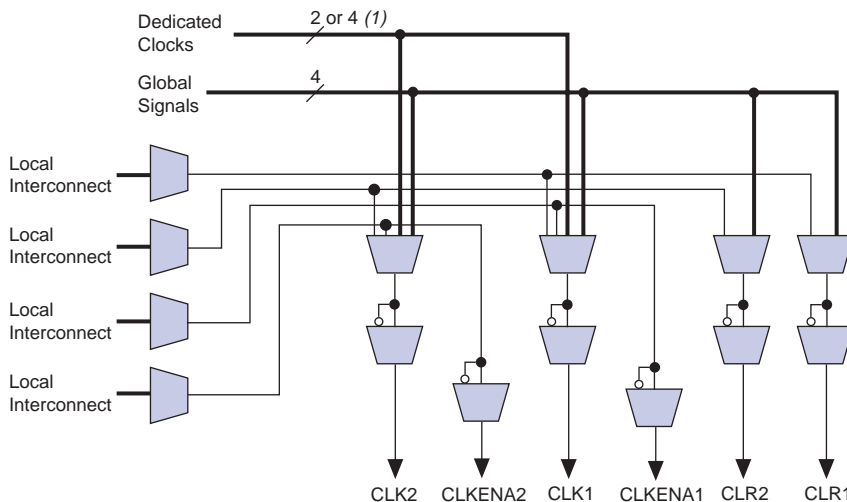


Figure 10. FastTrack Connection to Local Interconnect



The programmable register also supports an asynchronous clear function. Within the ESB, two asynchronous clears are generated from global signals and the local interconnect. Each macrocell can either choose between the two asynchronous clear signals or choose to not be cleared. Either of the two clear signals can be inverted within the ESB. Figure 15 shows the ESB control logic when implementing product-terms.

**Figure 15. ESB Product-Term Mode Control Logic**



**Note to Figure 15:**

(1) APEX 20KE devices have four dedicated clocks.

### Parallel Expanders

Parallel expanders are unused product terms that can be allocated to a neighboring macrocell to implement fast, complex logic functions. Parallel expanders allow up to 32 product terms to feed the macrocell OR logic directly, with two product terms provided by the macrocell and 30 parallel expanders provided by the neighboring macrocells in the ESB.

The Quartus II software Compiler can allocate up to 15 sets of up to two parallel expanders per set to the macrocells automatically. Each set of two parallel expanders incurs a small, incremental timing delay. Figure 16 shows the APEX 20K parallel expanders.

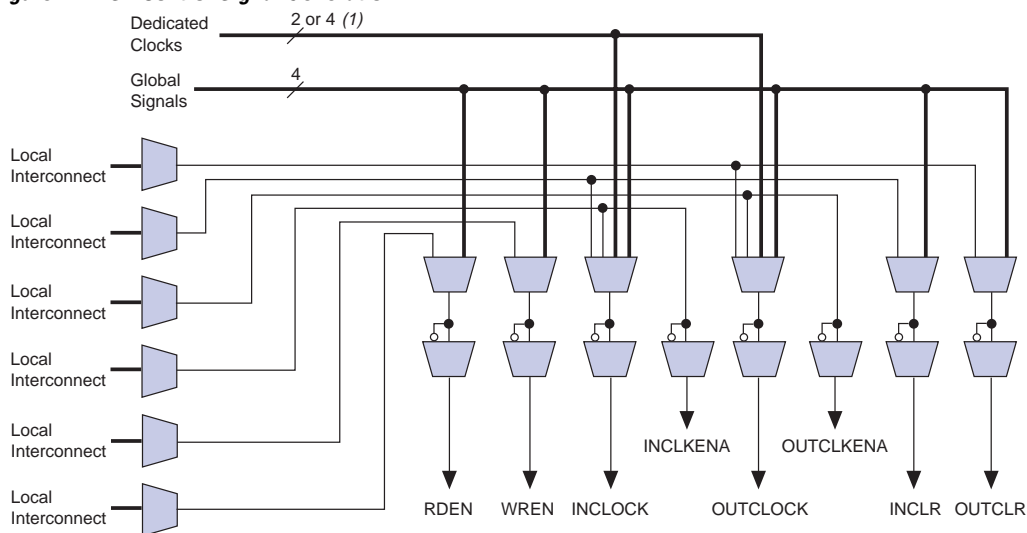


For more information on APEX 20KE devices and CAM, see *Application Note 119 (Implementing High-Speed Search Applications with APEX CAM)*.

## Driving Signals to the ESB

ESBs provide flexible options for driving control signals. Different clocks can be used for the ESB inputs and outputs. Registers can be inserted independently on the data input, data output, read address, write address, WE, and RE signals. The global signals and the local interconnect can drive the WE and RE signals. The global signals, dedicated clock pins, and local interconnect can drive the ESB clock signals. Because the LEs drive the local interconnect, the LEs can control the WE and RE signals and the ESB clock, clock enable, and asynchronous clear signals. [Figure 24](#) shows the ESB control signal generation logic.

**Figure 24. ESB Control Signal Generation**



**Note to Figure 24:**

(1) APEX 20KE devices have four dedicated clocks.

An ESB is fed by the local interconnect, which is driven by adjacent LEs (for high-speed connection to the ESB) or the MegaLAB interconnect. The ESB can drive the local, MegaLAB, or FastTrack Interconnect routing structure to drive LEs and IOEs in the same MegaLAB structure or anywhere in the device.

## Implementing Logic in ROM

In addition to implementing logic with product terms, the ESB can implement logic functions when it is programmed with a read-only pattern during configuration, creating a large LUT. With LUTs, combinatorial functions are implemented by looking up the results, rather than by computing them. This implementation of combinatorial functions can be faster than using algorithms implemented in general logic, a performance advantage that is further enhanced by the fast access times of ESBs. The large capacity of ESBs enables designers to implement complex functions in one logic level without the routing delays associated with linked LEs or distributed RAM blocks. Parameterized functions such as LPM functions can take advantage of the ESB automatically. Further, the Quartus II software can implement portions of a design with ESBs where appropriate.

## Programmable Speed/Power Control

APEX 20K ESBs offer a high-speed mode that supports very fast operation on an ESB-by-ESB basis. When high speed is not required, this feature can be turned off to reduce the ESB's power dissipation by up to 50%. ESBs that run at low power incur a nominal timing delay adder. This Turbo Bit™ option is available for ESBs that implement product-term logic or memory functions. An ESB that is not used will be powered down so that it does not consume DC current.

Designers can program each ESB in the APEX 20K device for either high-speed or low-power operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths operate at reduced power.

## I/O Structure

The APEX 20K IOE contains a bidirectional I/O buffer and a register that can be used either as an input register for external data requiring fast setup times, or as an output register for data requiring fast clock-to-output performance. IOEs can be used as input, output, or bidirectional pins. For fast bidirectional I/O timing, LE registers using local routing can improve setup times and OE timing. The Quartus II software Compiler uses the programmable inversion option to invert signals from the row and column interconnect automatically where appropriate. Because the APEX 20K IOE offers one output enable per pin, the Quartus II software Compiler can emulate open-drain operation efficiently.

The APEX 20K IOE includes programmable delays that can be activated to ensure zero hold times, minimum clock-to-output times, input IOE register-to-core register transfers, or core-to-output IOE register transfers. A path in which a pin directly drives a register may require the delay to ensure zero hold time, whereas a path in which a pin drives a register through combinatorial logic may not require the delay.

APEX 20KE devices include an enhanced IOE, which drives the FastRow interconnect. The FastRow interconnect connects a column I/O pin directly to the LAB local interconnect within two MegaLAB structures. This feature provides fast setup times for pins that drive high fan-outs with complex logic, such as PCI designs. For fast bidirectional I/O timing, LE registers using local routing can improve setup times and OE timing. The APEX 20KE IOE also includes direct support for open-drain operation, giving faster clock-to-output for open-drain signals. Some programmable delays in the APEX 20KE IOE offer multiple levels of delay to fine-tune setup and hold time requirements. The Quartus II software compiler can set these delays automatically to minimize setup time while providing a zero hold time.

**Table 11** describes the APEX 20KE programmable delays and their logic options in the Quartus II software.

<b>Table 11. APEX 20KE Programmable Delay Chains</b>	
<b>Programmable Delays</b>	<b>Quartus II Logic Option</b>
Input Pin to Core Delay	Decrease input delay to internal cells
Input Pin to Input Register Delay	Decrease input delay to input registers
Core to Output Register Delay	Decrease input delay to output register
Output Register $t_{CO}$ Delay	Increase delay to output pin
Clock Enable Delay	Increase clock enable delay

The register in the APEX 20KE IOE can be programmed to power-up high or low after configuration is complete. If it is programmed to power-up low, an asynchronous clear can control the register. If it is programmed to power-up high, an asynchronous preset can control the register. **Figure 26** shows how fast bidirectional I/O pins are implemented in APEX 20KE devices. This feature is useful for cases where the APEX 20KE device controls an active-low input or another device; it prevents inadvertent activation of the input upon power-up.



APEX 20KE devices also support the MultiVolt I/O interface feature. The APEX 20KE VCCINT pins must always be connected to a 1.8-V power supply. With a 1.8-V VCCINT level, input pins are 1.8-V, 2.5-V, and 3.3-V tolerant. The VCCIO pins can be connected to either a 1.8-V, 2.5-V, or 3.3-V power supply, depending on the I/O standard requirements. When the VCCIO pins are connected to a 1.8-V power supply, the output levels are compatible with 1.8-V systems. When VCCIO pins are connected to a 2.5-V power supply, the output levels are compatible with 2.5-V systems. When VCCIO pins are connected to a 3.3-V power supply, the output high is 3.3 V and compatible with 3.3-V or 5.0-V systems. An APEX 20KE device is 5.0-V tolerant with the addition of a resistor.

Table 13 summarizes APEX 20KE MultiVolt I/O support.

<b>Table 13. APEX 20KE MultiVolt I/O Support</b> <i>Note (1)</i>								
V <sub>CCIO</sub> (V)	Input Signals (V)				Output Signals (V)			
	1.8	2.5	3.3	5.0	1.8	2.5	3.3	5.0
1.8	✓	✓	✓		✓			
2.5	✓	✓	✓			✓		
3.3	✓	✓	✓	(2)			✓(3)	

**Notes to Table 13:**

- (1) The PCI clamping diode must be disabled to drive an input with voltages higher than V<sub>CCIO</sub>, except for the 5.0-V input case.
- (2) An APEX 20KE device can be made 5.0-V tolerant with the addition of an external resistor. You also need a PCI clamp and series resistor.
- (3) When V<sub>CCIO</sub> = 3.3 V, an APEX 20KE device can drive a 2.5-V device with 3.3-V tolerant inputs.

## ClockLock & ClockBoost Features

APEX 20K devices support the ClockLock and ClockBoost clock management features, which are implemented with PLLs. The ClockLock circuitry uses a synchronizing PLL that reduces the clock delay and skew within a device. This reduction minimizes clock-to-output and setup times while maintaining zero hold times. The ClockBoost circuitry, which provides a clock multiplier, allows the designer to enhance device area efficiency by sharing resources within the device. The ClockBoost circuitry allows the designer to distribute a low-speed clock and multiply that clock on-device. APEX 20K devices include a high-speed clock tree; unlike ASICs, the user does not have to design and optimize the clock tree. The ClockLock and ClockBoost features work in conjunction with the APEX 20K device's high-speed clock to provide significant improvements in system performance and band-width. Devices with an X-suffix on the ordering code include the ClockLock circuit.

The ClockLock and ClockBoost features in APEX 20K devices are enabled through the Quartus II software. External devices are not required to use these features.

### *Clock Phase & Delay Adjustment*

The APEX 20KE ClockShift feature allows the clock phase and delay to be adjusted. The clock phase can be adjusted by 90° steps. The clock delay can be adjusted to increase or decrease the clock delay by an arbitrary amount, up to one clock period.

### *LVDS Support*

Two PLLs are designed to support the LVDS interface. When using LVDS, the I/O clock runs at a slower rate than the data transfer rate. Thus, PLLs are used to multiply the I/O clock internally to capture the LVDS data. For example, an I/O clock may run at 105 MHz to support 840 megabits per second (Mbps) LVDS data transfer. In this example, the PLL multiplies the incoming clock by eight to support the high-speed data transfer. You can use PLLs in EP20K400E and larger devices for high-speed LVDS interfacing.

### *Lock Signals*

The APEX 20KE ClockLock circuitry supports individual LOCK signals. The LOCK signal drives high when the ClockLock circuit has locked onto the input clock. The LOCK signals are optional for each ClockLock circuit; when not used, they are I/O pins.

## **ClockLock & ClockBoost Timing Parameters**

For the ClockLock and ClockBoost circuitry to function properly, the incoming clock must meet certain requirements. If these specifications are not met, the circuitry may not lock onto the incoming clock, which generates an erroneous clock within the device. The clock generated by the ClockLock and ClockBoost circuitry must also meet certain specifications. If the incoming clock meets these requirements during configuration, the APEX 20K ClockLock and ClockBoost circuitry will lock onto the clock during configuration. The circuit will be ready for use immediately after configuration. In APEX 20KE devices, the clock input standard is programmable, so the PLL cannot respond to the clock until the device is configured. The PLL locks onto the input clock as soon as configuration is complete. [Figure 30](#) shows the incoming and generated clock specifications.



For more information on ClockLock and ClockBoost circuitry, see *Application Note 115: Using the ClockLock and ClockBoost PLL Features in APEX Devices*.

## IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

All APEX 20K devices provide JTAG BST circuitry that complies with the IEEE Std. 1149.1-1990 specification. JTAG boundary-scan testing can be performed before or after configuration, but not during configuration. APEX 20K devices can also use the JTAG port for configuration with the Quartus II software or with hardware using either Jam Files (.jam) or Jam Byte-Code Files (.jbc). Finally, APEX 20K devices use the JTAG port to monitor the logic operation of the device with the SignalTap embedded logic analyzer. APEX 20K devices support the JTAG instructions shown in Table 19. Although EP20K1500E devices support the JTAG BYPASS and SignalTap instructions, they do not support boundary-scan testing or the use of the JTAG port for configuration.

**Table 19. APEX 20K JTAG Instructions**

JTAG Instruction	Description
SAMPLE/PRELOAD	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern to be output at the device pins. Also used by the SignalTap embedded logic analyzer.
EXTEST	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.
BYPASS (1)	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through selected devices to adjacent devices during normal device operation.
USERCODE	Selects the 32-bit USERCODE register and places it between the TDI and TDO pins, allowing the USERCODE to be serially shifted out of TDO.
IDCODE	Selects the IDCODE register and places it between TDI and TDO, allowing the IDCODE to be serially shifted out of TDO.
ICR Instructions	Used when configuring an APEX 20K device via the JTAG port with a MasterBlaster™ or ByteBlasterMV™ download cable, or when using a Jam File or Jam Byte-Code File via an embedded processor.
SignalTap Instructions (1)	Monitors internal device operation with the SignalTap embedded logic analyzer.

**Note to Table 19:**

(1) The EP20K1500E device supports the JTAG BYPASS instruction and the SignalTap instructions.

**Table 25. APEX 20K 5.0-V Tolerant Device DC Operating Conditions (Part 2 of 2)** Notes (2), (7), (8)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{OL}$	3.3-V low-level TTL output voltage	$I_{OL} = 12 \text{ mA DC}$ , $V_{CCIO} = 3.00 \text{ V}$ (11)			0.45	V
	3.3-V low-level CMOS output voltage	$I_{OL} = 0.1 \text{ mA DC}$ , $V_{CCIO} = 3.00 \text{ V}$ (11)			0.2	V
	3.3-V low-level PCI output voltage	$I_{OL} = 1.5 \text{ mA DC}$ , $V_{CCIO} = 3.00 \text{ to } 3.60 \text{ V}$ (11)			$0.1 \times V_{CCIO}$	V
	2.5-V low-level output voltage	$I_{OL} = 0.1 \text{ mA DC}$ , $V_{CCIO} = 2.30 \text{ V}$ (11)			0.2	V
		$I_{OL} = 1 \text{ mA DC}$ , $V_{CCIO} = 2.30 \text{ V}$ (11)			0.4	V
		$I_{OL} = 2 \text{ mA DC}$ , $V_{CCIO} = 2.30 \text{ V}$ (11)			0.7	V
$I_I$	Input pin leakage current	$V_I = 5.75 \text{ to } -0.5 \text{ V}$	-10		10	$\mu\text{A}$
$I_{OZ}$	Tri-stated I/O pin leakage current	$V_O = 5.75 \text{ to } -0.5 \text{ V}$	-10		10	$\mu\text{A}$
$I_{CC0}$	$V_{CC}$ supply current (standby) (All ESBs in power-down mode)	$V_I = \text{ground}$ , no load, no toggling inputs, -1 speed grade (12)		10		mA
		$V_I = \text{ground}$ , no load, no toggling inputs, -2, -3 speed grades (12)		5		mA
$R_{CONF}$	Value of I/O pin pull-up resistor before and during configuration	$V_{CCIO} = 3.0 \text{ V}$ (13)	20		50	W
		$V_{CCIO} = 2.375 \text{ V}$ (13)	30		80	W



For DC Operating Specifications on APEX 20KE I/O standards, please refer to *Application Note 117 (Using Selectable I/O Standards in Altera Devices)*.

**Table 30. APEX 20KE Device Capacitance** Note (15)

Symbol	Parameter	Conditions	Min	Max	Unit
$C_{IN}$	Input capacitance	$V_{IN} = 0\text{ V}$ , $f = 1.0\text{ MHz}$		8	pF
$C_{INCLK}$	Input capacitance on dedicated clock pin	$V_{IN} = 0\text{ V}$ , $f = 1.0\text{ MHz}$		12	pF
$C_{OUT}$	Output capacitance	$V_{OUT} = 0\text{ V}$ , $f = 1.0\text{ MHz}$		8	pF

**Notes to Tables 27 through 30:**

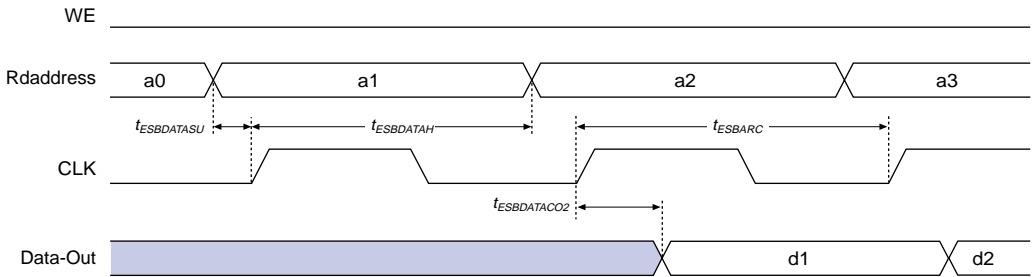
- (1) See the *Operating Requirements for Altera Devices Data Sheet*.
- (2) Minimum DC input is  $-0.5\text{ V}$ . During transitions, the inputs may undershoot to  $-2.0\text{ V}$  or overshoot to  $5.75\text{ V}$  for input currents less than  $100\text{ mA}$  and periods shorter than  $20\text{ ns}$ .
- (3) Numbers in parentheses are for industrial-temperature-range devices.
- (4) Maximum  $V_{CC}$  rise time is  $100\text{ ms}$ , and  $V_{CC}$  must rise monotonically.
- (5) Minimum DC input is  $-0.5\text{ V}$ . During transitions, the inputs may undershoot to  $-2.0\text{ V}$  or overshoot to the voltage shown in the following table based on input duty cycle for input currents less than  $100\text{ mA}$ . The overshoot is dependent upon duty cycle of the signal. The DC case is equivalent to  $100\%$  duty cycle.

$V_{IN}$	Max. Duty Cycle
$4.0\text{ V}$	$100\%$ (DC)
$4.1$	$90\%$
$4.2$	$50\%$
$4.3$	$30\%$
$4.4$	$17\%$
$4.5$	$10\%$
- (6) All pins, including dedicated inputs, clock, I/O, and JTAG pins, may be driven before  $V_{CCINT}$  and  $V_{CCIO}$  are powered.
- (7) Typical values are for  $T_A = 25^\circ\text{ C}$ ,  $V_{CCINT} = 1.8\text{ V}$ , and  $V_{CCIO} = 1.8\text{ V}$ ,  $2.5\text{ V}$  or  $3.3\text{ V}$ .
- (8) These values are specified under the APEX 20KE device recommended operating conditions, shown in Table 24 on page 60.
- (9) Refer to *Application Note 117 (Using Selectable I/O Standards in Altera Devices)* for the  $V_{IH}$ ,  $V_{IL}$ ,  $V_{OH}$ ,  $V_{OL}$ , and  $I_I$  parameters when  $V_{CCIO} = 1.8\text{ V}$ .
- (10) The APEX 20KE input buffers are compatible with  $1.8\text{-V}$ ,  $2.5\text{-V}$  and  $3.3\text{-V}$  (LVTTTL and LVCMOS) signals. Additionally, the input buffers are  $3.3\text{-V}$  PCI compliant. Input buffers also meet specifications for GTL+, CTT, AGP, SSTL-2, SSTL-3, and HSTL.
- (11) The  $I_{OH}$  parameter refers to high-level TTL, PCI, or CMOS output current.
- (12) The  $I_{OL}$  parameter refers to low-level TTL, PCI, or CMOS output current. This parameter applies to open-drain pins as well as output pins.
- (13) This value is specified for normal device operation. The value may vary during power-up.
- (14) Pin pull-up resistance values will be lower if an external source drives the pin higher than  $V_{CCIO}$ .
- (15) Capacitance is sample-tested only.

Figure 33 shows the relationship between  $V_{CCIO}$  and  $V_{CCINT}$  for  $3.3\text{-V}$  PCI compliance on APEX 20K devices.

**Figure 39. ESB Synchronous Timing Waveforms**

**ESB Synchronous Read**



**ESB Synchronous Write (ESB Output Registers Used)**

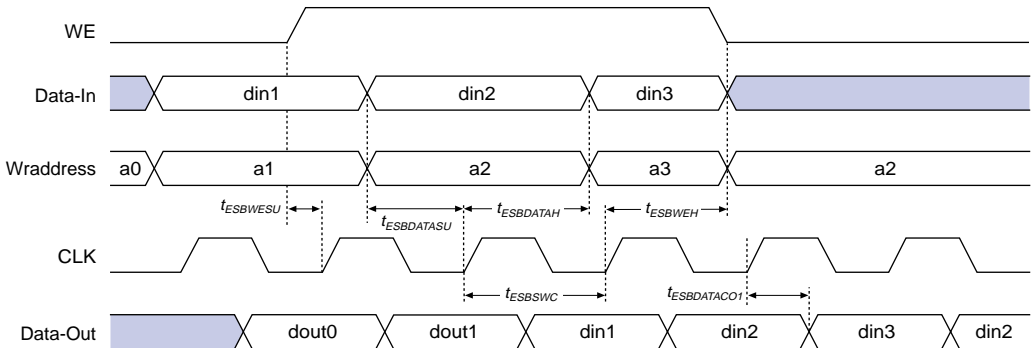


Figure 40 shows the timing model for bidirectional I/O pin timing.

Note to [Tables 32 and 33](#):

(1) These timing parameters are sample-tested only.

[Tables 34 through 37](#) show APEX 20KE LE, ESB, routing, and functional timing microparameters for the  $f_{MAX}$  timing model.

**Table 34. APEX 20KE LE Timing Microparameters**

Symbol	Parameter
$t_{SU}$	LE register setup time before clock
$t_H$	LE register hold time after clock
$t_{CO}$	LE register clock-to-output delay
$t_{LUT}$	LUT delay for data-in to data-out

**Table 35. APEX 20KE ESB Timing Microparameters**

Symbol	Parameter
$t_{ESBARC}$	ESB Asynchronous read cycle time
$t_{ESBSRC}$	ESB Synchronous read cycle time
$t_{ESBAWC}$	ESB Asynchronous write cycle time
$t_{ESBSWC}$	ESB Synchronous write cycle time
$t_{ESBWASU}$	ESB write address setup time with respect to WE
$t_{ESBWAH}$	ESB write address hold time with respect to WE
$t_{ESBWDSU}$	ESB data setup time with respect to WE
$t_{ESBWdH}$	ESB data hold time with respect to WE
$t_{ESBRASU}$	ESB read address setup time with respect to RE
$t_{ESBRAH}$	ESB read address hold time with respect to RE
$t_{ESBWESU}$	ESB WE setup time before clock when using input register
$t_{ESBWEH}$	ESB WE hold time after clock when using input register
$t_{ESBDATASU}$	ESB data setup time before clock when using input register
$t_{ESBDATAH}$	ESB data hold time after clock when using input register
$t_{ESBWADDRSU}$	ESB write address setup time before clock when using input registers
$t_{ESBRADDRSU}$	ESB read address setup time before clock when using input registers
$t_{ESBDATACO1}$	ESB clock-to-output delay when using output registers
$t_{ESBDATACO2}$	ESB clock-to-output delay without output registers
$t_{ESBDD}$	ESB data-in to data-out delay for RAM mode
$t_{PD}$	ESB Macrocell input to non-registered output
$t_{PTERMSU}$	ESB Macrocell register setup time before clock
$t_{PTERMCO}$	ESB Macrocell register clock-to-output delay

**Table 42. EP20K400  $f_{MAX}$  Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Units
	Min	Max	Min	Max	Min	Max	
$t_{SU}$	0.1		0.3		0.6		ns
$t_H$	0.5		0.8		0.9		ns
$t_{CO}$		0.1		0.4		0.6	ns
$t_{LUT}$		1.0		1.2		1.4	ns
$t_{ESBRC}$		1.7		2.1		2.4	ns
$t_{ESBWC}$		5.7		6.9		8.1	ns
$t_{ESBWESU}$	3.3		3.9		4.6		ns
$t_{ESBDATASU}$	2.2		2.7		3.1		ns
$t_{ESBDATAH}$	0.6		0.8		0.9		ns
$t_{ESBADDRSU}$	2.4		2.9		3.3		ns
$t_{ESBDATACO1}$		1.3		1.6		1.8	ns
$t_{ESBDATACO2}$		2.5		3.1		3.6	ns
$t_{ESBDD}$		2.5		3.3		3.6	ns
$t_{PD}$		2.5		3.1		3.6	ns
$t_{PTERMSU}$	1.7		2.1		2.4		ns
$t_{PTERMCO}$		1.0		1.2		1.4	ns
$t_{F1-4}$		0.4		0.5		0.6	ns
$t_{F5-20}$		2.6		2.8		2.9	ns
$t_{F20+}$		3.7		3.8		3.9	ns
$t_{CH}$	2.0		2.5		3.0		ns
$t_{CL}$	2.0		2.5		3.0		ns
$t_{CLRP}$	0.5		0.6		0.8		ns
$t_{PREP}$	0.5		0.5		0.5		ns
$t_{ESBCH}$	2.0		2.5		3.0		ns
$t_{ESBCL}$	2.0		2.5		3.0		ns
$t_{ESBWP}$	1.5		1.9		2.2		ns
$t_{ESBRP}$	1.0		1.2		1.4		ns

Tables 43 through 48 show the I/O external and external bidirectional timing parameter values for EP20K100, EP20K200, and EP20K400 APEX 20K devices.



**Table 90. EP20K400E External Bidirectional Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{\text{INSUBIDIR}}$	2.93		3.23		3.44		ns
$t_{\text{INHBIDIR}}$	0.00		0.00		0.00		ns
$t_{\text{OUTCOBIDIR}}$	2.00	5.25	2.00	5.79	2.00	6.32	ns
$t_{\text{XZBIDIR}}$		5.95		6.77		7.12	ns
$t_{\text{ZXBIDIR}}$		5.95		6.77		7.12	ns
$t_{\text{INSUBIDIRPLL}}$	4.31		4.76		-		ns
$t_{\text{INHBIDIRPLL}}$	0.00		0.00		-		ns
$t_{\text{OUTCOBIDIRPLL}}$	0.50	2.25	0.50	2.45	-	-	ns
$t_{\text{XZBIDIRPLL}}$		2.94		3.43		-	ns
$t_{\text{ZXBIDIRPLL}}$		2.94		3.43		-	ns

Tables 91 through 96 describe  $f_{\text{MAX}}$  LE Timing Microparameters,  $f_{\text{MAX}}$  ESB Timing Microparameters,  $f_{\text{MAX}}$  Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K600E APEX 20KE devices.

**Table 91. EP20K600E  $f_{\text{MAX}}$  LE Timing Microparameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{\text{SU}}$	0.16		0.16		0.17		ns
$t_{\text{H}}$	0.29		0.33		0.37		ns
$t_{\text{CO}}$		0.65		0.38		0.49	ns
$t_{\text{LUT}}$		0.70		1.00		1.30	ns

**Table 106. EP20K1500E Minimum Pulse Width Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>CH</sub>	1.25		1.43		1.67		ns
t <sub>CL</sub>	1.25		1.43		1.67		ns
t <sub>CLRP</sub>	0.20		0.20		0.20		ns
t <sub>PREP</sub>	0.20		0.20		0.20		ns
t <sub>ESBCH</sub>	1.25		1.43		1.67		ns
t <sub>ESBCL</sub>	1.25		1.43		1.67		ns
t <sub>ESBWP</sub>	1.28		1.51		1.65		ns
t <sub>ESBRP</sub>	1.11		1.29		1.41		ns

**Table 107. EP20K1500E External Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>INSU</sub>	3.09		3.30		3.58		ns
t <sub>INH</sub>	0.00		0.00		0.00		ns
t <sub>OUTCO</sub>	2.00	6.18	2.00	6.81	2.00	7.36	ns
t <sub>INSUPLL</sub>	1.94		2.08		-		ns
t <sub>INHPLL</sub>	0.00		0.00		-		ns
t <sub>OUTCOPLL</sub>	0.50	2.67	0.50	2.99	-	-	ns

**Table 108. EP20K1500E External Bidirectional Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{\text{INSUBIDIR}}$	3.47		3.68		3.99		ns
$t_{\text{INHBIDIR}}$	0.00		0.00		0.00		ns
$t_{\text{OUTCOBIDIR}}$	2.00	6.18	2.00	6.81	2.00	7.36	ns
$t_{\text{XZBIDIR}}$		6.91		7.62		8.38	ns
$t_{\text{ZXBIDIR}}$		6.91		7.62		8.38	ns
$t_{\text{INSUBIDIRPLL}}$	3.05		3.26				ns
$t_{\text{INHBIDIRPLL}}$	0.00		0.00				ns
$t_{\text{OUTCOBIDIRPLL}}$	0.50	2.67	0.50	2.99			ns
$t_{\text{XZBIDIRPLL}}$		3.41		3.80			ns
$t_{\text{ZXBIDIRPLL}}$		3.41		3.80			ns

Tables 109 and 110 show selectable I/O standard input and output delays for APEX 20KE devices. If you select an I/O standard input or output delay other than LVCMOS, add or subtract the selected speed grade to or from the LVCMOS value.

**Table 109. Selectable I/O Standard Input Delays**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min
LVCMOS		0.00		0.00		0.00	ns
LVTTL		0.00		0.00		0.00	ns
2.5 V		0.00		0.04		0.05	ns
1.8 V		-0.11		0.03		0.04	ns
PCI		0.01		0.09		0.10	ns
GTL+		-0.24		-0.23		-0.19	ns
SSTL-3 Class I		-0.32		-0.21		-0.47	ns
SSTL-3 Class II		-0.08		0.03		-0.23	ns
SSTL-2 Class I		-0.17		-0.06		-0.32	ns
SSTL-2 Class II		-0.16		-0.05		-0.31	ns
LVDS		-0.12		-0.12		-0.12	ns
CTT		0.00		0.00		0.00	ns
AGP		0.00		0.00		0.00	ns

**Table 110. Selectable I/O Standard Output Delays**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min
LVC MOS		0.00		0.00		0.00	ns
LVTTL		0.00		0.00		0.00	ns
2.5 V		0.00		0.09		0.10	ns
1.8 V		2.49		2.98		3.03	ns
PCI		−0.03		0.17		0.16	ns
GTL+		0.75		0.75		0.76	ns
SSTL-3 Class I		1.39		1.51		1.50	ns
SSTL-3 Class II		1.11		1.23		1.23	ns
SSTL-2 Class I		1.35		1.48		1.47	ns
SSTL-2 Class II		1.00		1.12		1.12	ns
LVDS		−0.48		−0.48		−0.48	ns
CTT		0.00		0.00		0.00	ns
AGP		0.00		0.00		0.00	ns

## Power Consumption

To estimate device power consumption, use the interactive power calculator on the Altera web site at <http://www.altera.com>.

## Configuration & Operation

The APEX 20K architecture supports several configuration schemes. This section summarizes the device operating modes and available device configuration schemes.

### Operating Modes

The APEX architecture uses SRAM configuration elements that require configuration data to be loaded each time the circuit powers up. The process of physically loading the SRAM data into the device is called configuration. During initialization, which occurs immediately after configuration, the device resets registers, enables I/O pins, and begins to operate as a logic device. The I/O pins are tri-stated during power-up, and before and during configuration. Together, the configuration and initialization processes are called *command mode*; normal device operation is called *user mode*.

Before and during device configuration, all I/O pins are pulled to  $V_{CCIO}$  by a built-in weak pull-up resistor.



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